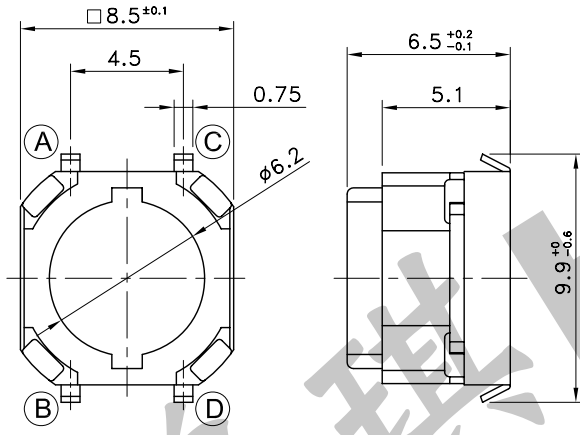
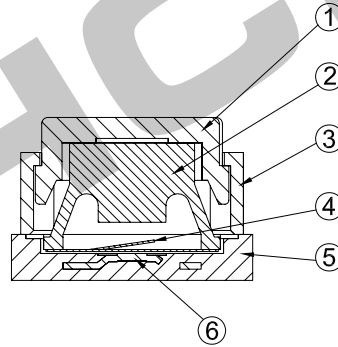


6	Stationary Contact	Brass	Ag Palating
5	Mounting Base	Polyphthalamide	
4	Movable Contact	Stainless Steel for Spring	One Side Ag Plating
3	Cover Plate	Polyamide Resin	
2	Push Plate (2)	Silicone Rubber	
1	Push Plate (1)	Polyphthalamide	
No.	Parts	Material	Finish

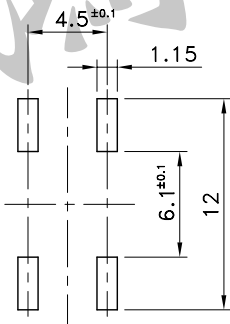
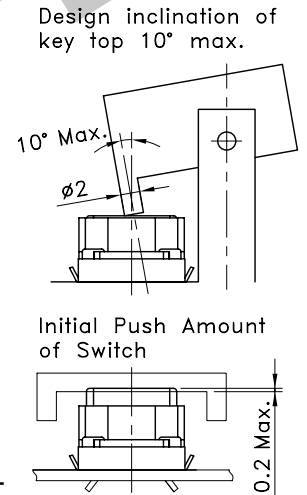
Part No.	Force
STS-116-D1	400±80gf
STS-116-E1	500±150gf



P.C.B TERMINAL POSITION

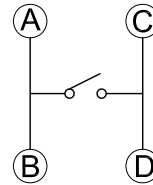


CIRCUIT ARRANGEMENT



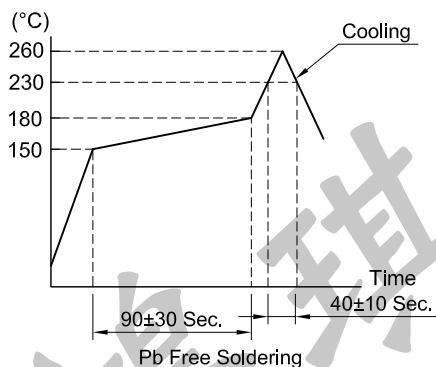
(Solder Thickness: $t=0.15\pm0.03$)

SOLDERING CONDITIONS



SPECIFICATIONS

- Rating : DC2V 10 μ A ~ DC 12V 50mA
- Contact Resistance : 100m Ω Max.
- Insulation Resistance : 100M Ω Min. at DC 100V
- Dielectric strength : AC 250V for 1 Minute
- Stroke : 1±0.2 mm
- Life : 100,000 Cycles
- Package : 1,000 Pcs/Reel
- Operating Temperature Range : -40~+85°C
- Storage Temperature Range : -40~+85°C (Bulk)
-20~+60°C (Taping)
- Reflow Soldering Profile : According Reflow Profile
2 Times
- Manual Soldering : Solder Temperature 350°C Max.
Solder Time 3 Sec. Max.



REVISION:		DATE:		REVISION:		DATE:	
UNIT:mm		THIRD ANGLE PROJECTION METHOD		TOL. UNLESS OTHERWISE STATED:±0.2		CODE NO.: HCH-1509-1	
ISSUED		CONFIRMED		PART NO.		STS-116-D1	
John		Elvis		HCH HORNG CHIH		STS-116-E1	
2013.01.28		2013.01.28		ISO9001 Certified ISO14001 Certified 鴻琪股份有限公司			